

Batch Vacuum Soldering Systems
In-Line Vacuum Soldering System
Conveyor Furnaces for MLCC, HTCC, LTCC
Conveyor Furnaces for Thick Film Application
Conveyor Furnaces for Drying, Curing
Conveyor Furnaces for Tailored Solutions

2310

VLO 180 / 300 Vacuum Soldering System

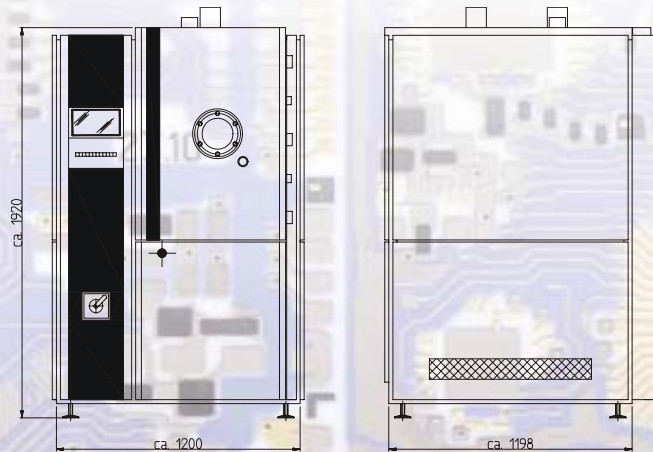


The VLO Series vacuum soldering systems are equipped with integrated heating and cooling platens. The VLO Series are ideal for production requiring flux, flux-free, void-free solder processing. The VLO Series provides simple operations, easy process profiles editing and recipe storing via the touch screen operated process control computer. Serial interface allows data transfer to a PC, off line programming and permitting remote service monitoring. The individually controlled rigid platens allow flexible mixed loads solder processing up to 450 °C. Process atmospheres available are nitrogen (N₂), full hydrogen (100% H₂), forming gas (N₂/H₂), formic acid (HCOOH) and other specialty gases

Typical Applications

- Void-Free, Flux-Free and Flux Soldering
- Soldering of Power Semiconductors
- Soldering of Multi-Chip Assemblies
- Hybrid Microelectronics Assemblies
- Optoelectronic Packaging
- Military Electronics Packaging

System Dimensions



in mm

Technical Data

Operating Temperature	RT to 450 °C ± 5
Thermal Work Zone	VLO 180 1,122 in ² (7,239 cm ²) VLO 300 1,870 in ² (12,065 cm ²)
Work Surface Height	4 in (@10 cm)
Heat Rate	15 ~ 30 °C/min
Cool Rate	70 ~ 180 °C/min
Max. Load	33 lbs (15 kg) per platen
Vacuum Level	3.75 mTorr (0.005 mBar)
Vacuum Speed	38 CFM (65 m³/h)
Power supply	22-37 kW, 3 Phase, 208/480, 60Hz
Process Gases	N₂, H₂, Forming Gas, Formic Acid (optional other gases)
Gas Line Pressure	73 ~ 116 psig (5 - 8 bar)
Cooling Water	2.5 GPM (10 lpm)
Dimension (WxDxH)	49x54x76in (124x137x192cm)
Weight	2,250 lbs. (1,022 kg)

www.centrothermtech.com

centrotherm Technologies
250 North St. Unit A8
Danvers, MA 01923
Phone: (978) 777-9859
Fax: (978) 774-5413
info@centrotherm.info

Wafer Processing: microelectronics, power electronics, sensor technology, MEMS
Horizontal Furnace: annealing, oxidation, diffusion, LPCVD, PECVD, RTP, RTCVD
Environmental Technology: complete spectrum of abatement systems
Backend Processing: vacuum soldering, thick film, DCB, brazing, reflow, drying
Photovoltaic: complete turnkey solution, engineering, production equipment
Equipment, Applications, Global Service